SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995

- 3-State I/O-Type Read-Back Inputs
- Bus-Structured Pinout
- T/C Determines True or Complementary Data at Q Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

description

These 8-bit latches are designed specifically for storing the contents of the input data bus and providing the capability of reading back the stored data onto the input data bus. The Q outputs are designed with bus-driving capability.

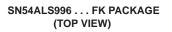
The edge-triggered flip-flops enter the data on the low-to-high transition of the clock (CLK) input when the enable (\overline{EN}) input is low. Data can be read back onto the data inputs by taking the read (\overline{RD}) input low, in addition to having \overline{EN} low. When \overline{EN} is high, both the read-back and write modes are disabled. Transitions on \overline{EN} should only be made with CLK high to prevent false clocking.

The polarity of the Q outputs can be controlled by the polarity (T/\overline{C}) input. When T/\overline{C} is high, Q is the same as is stored in the flip-flops. When T/\overline{C} is low, the output data is inverted. The Q outputs can be placed in the high-impedance state by taking the output-enable (\overline{OE}) input high. \overline{OE} does not affect the internal operation of the register. Old data can be retained or new data can be entered while the outputs are off.

A low level at the clear (CLR) input resets the internal registers low. The clear function is asynchronous and overrides all other register functions.

SN74ALS996 . (DW		IT PACKAGE
1D 🛛	1 U	24]v _{cc}
2D [2	23] 1Q
3D [3	22] 2Q
4D [4	21] 3Q
5D [5	20] 4Q
6D [6	19] 5Q
7D [7	18] 6Q
8D [8	17] 7Q
EN [9	16] 8Q
RD [10	15] <u>OE</u>
CLK [11	14] T/ <u>C</u>
GND [12	13] CLR

SN54ALS996 . . . JT PACKAGE



			ЗD	2D	1 0	S	V _{CC}	ą	2Q		
	1					ш					
4D	þ	5	4	3	2	1	28	27		25 C	3Q
5D	р	6							2	24	4Q
6D	þ	7							2	23[5Q
NC		8							2	22	NC
7D	þ	9							2	21	6Q
8D	D	1	0						2	20[7Q
ΕN	b	1	1							19[8Q
	Γ		12	13	14	15	16	17	18		
	_		ßD	CLK	GND	S N	CLR	ЦQ Ц			1

NC - No internal connection

The -1 version of the SN74ALS996 is identical to the standard version, except that the recommended maximum I_{OL} for the -1 version is increased to 48 mA. There is no -1 version of the SN54ALS996.

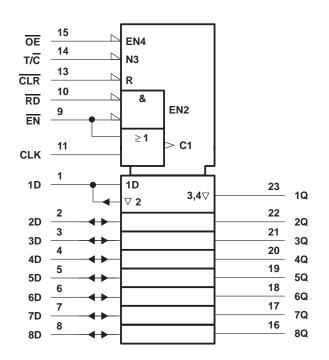
The SN54ALS996 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS996 is characterized for operation from 0° C to 70° C.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



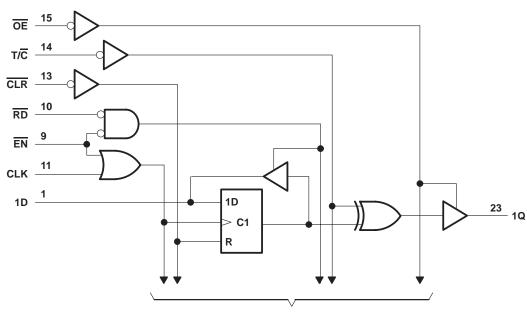
SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (positive logic)

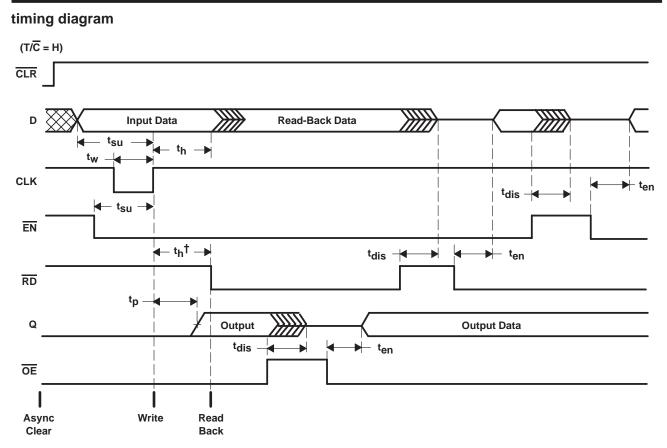


To Seven Other Channels

Pin numbers shown are for the DW, JT, and NT packages.



SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995



[†] This hold time ensures that the read-back circuit will not create a conflict on the input data bus.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, VI (OE, RD, EN, CLK, CLR, and T/C)	
Voltage applied to D inputs and to disabled 3-state outputs	5.5 V
Operating free-air temperature range, T _A : SN54ALS996	-55°C to 125°C
SN74ALS996	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995

recommended operating conditions

			SN	SN54ALS996		SN74ALS996			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
		All inputs				2				
VIH	High-level input voltage	All inputs except OE, RD	2						V	
		OE, RD	2.2							
VIL	Low-level input voltage				0.8			0.8	V	
lau	High-level output current	Q			-1			-2.6	mA	
ЮН	nigh-level output current	D			-0.4	AX MIN NOM MAX 5.5 4.5 5 5.5 2 -2 -2 0.8 0.8 0.8 -1 -2.6 -2.6 0.4 -0.4 -0.4 12 24 48^{\dagger} 8 8 8 35 0 35 10 14.5 114.5 14.5 15 10 10 15 10 5 5 5	MA			
IOL	Low-level output current	Q			12			24		
		Q						48†	mA	
		D			8			8		
fclock	Clock frequency		0		35	0		35	MHZ	
		CLR low	10			10				
IOH IOL ^f clock	Pulse duration	CLK low	14.5			14.5			ns	
		CLK high	14.5			14.5				
		Data before CLK [↑]	15			15				
•	Setup time	EN low before CLK [↑]	10			10				
lsu		CLK high before EN↑‡	15			15			ns	
		CLR high (inactive) before CLK [↑]	10			10				
		Data after CLK↑	1			0				
^t h	Hold time	EN low after CLK↑	5			5			ns	
		RD high after CLK [↑] §	5			5				
Тд	Operating free-air temperatur	e	-55		125	0		70	°C	

[†] Applies only to the -1 version and only if V_{CC} is maintained between 4.75 V and 5.25 V [‡] This setup time ensures that EN will not false clock the data register. § This hold time ensures that there will be no conflict on the input data bus.



SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995

PARAMETER TEST		TEAT O			54ALS9	96	SN74ALS996			
		TEST G			TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.5 V,	l _l = – 18 mA			-1.2			-1.2	V
	All outputs	V _{CC} = 4.5 V to 5.5 V,	I _{OH} = - 0.4 mA	V _{CC} -2	2		V _{CC} -2	2		
Vон			I _{OH} = – 1 mA	2.4	3.2					V
	Q	$V_{CC} = 4.5 V$	I _{OH} = - 2.6 mA				2.4	3.2		
			I _{OL} = 4 mA		0.25	0.4				v
	D	$V_{CC} = 4.5 V$	I _{OL} = 8 mA					0.35	0.5	
VOL			I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
	Q	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	
			I _{OL} = 48 mA‡					0.35	0.5	
IOZH	Q	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ
IOZL	Q	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ
	D inputs	V _{CC} = 5.5 V	V _I = 5.5 V			0.1			0.1	A
łı	All others		V _I = 7 V			0.1			0.1	mA
	D inputs§					20			20	
ΙΗ	All others	$-V_{CC} = 5.5 V,$	V ₁ = 2.7 V			20			20	μA
	D inputs§		$V_{I} = 0.4 V$			-0.1			-0.1	
ΊL	All others	$V_{CC} = 5.5 V,$				-0.1			-0.1	mA
IO _l		<u>V_{CC}</u> = 5.5 V, CLR = 2.5 V	V _O = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		35	55		35	55	
ICC		<u>V_CC = 5</u> .5 V, EN, RD low	Outputs low		55	85		55	85	mA
			Outputs disabled		42	65		42	65	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] Applies only to the -1 version and only if V_{CC} is maintained between 4.75 V and 5.25 V [§] For I/O ports (Q_A thru Q_H), the parameters I_{IH} and I_{IL} include the off-state output current. [¶] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.



SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995

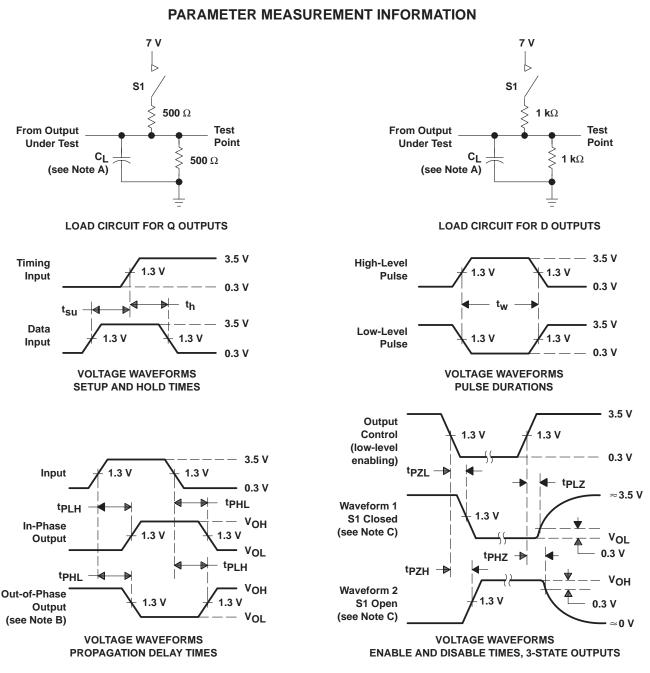
switching characteristics (see Figure 1)

PARAMETER	FROM	ТО (ОИТРИТ)	VC CL TA	$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_L = 50 \text{ pF},$ $T_A = \text{MIN to MAX}^{\dagger}$				
	(INPUT)		SN54A	LS996	SN74ALS996		UNIT	
			MIN	MAX	MIN	MAX		
f _{max}			35		35		MHz	
^t PLH	CLK		5	30	5	28		
^t PHL	(T/ C = H or L)	Q	5	24	5	28	ns	
^t PLH	$\overline{\text{CLR}}$ (T/ $\overline{\text{C}}$ = L)		5	27	7	27		
^t PHL	$\overline{\text{CLR}}$ (T/ $\overline{\text{C}}$ = H)	Q	5	23	7	23	ns	
^t PLH	-15		4	23	5	23	ns	
^t PHL	T/C	Q	5	23	5	23		
^t PHL	CLR	D	5	30	8	30	ns	
ten‡		_	2	18	3	16		
t _{dis} §	RD	D	1	19	3	19	ns	
t _{en} ‡			2	17	3	16		
t _{dis} §	EN	D	1	19	3	19	ns	
_{ten} ‡			2	15	4	15		
t _{dis} §	OE	Q	1	11	1	10	ns	

t For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. t ten = tPZH or tPZL \$ tdis = tPHZ or tPLZ



SDAS098B - OCTOBER 1984 - REVISED JANUARY 1995



NOTES: A. CL includes probe and jig capacitance.

B. When measuring propagation delay times of 3-state outputs, switch S1 is open.

C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. All input pulses have the following characteristics: PRR ≤ 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.

Figure 1. Load Circuits and Voltage Waveforms



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